



PRESS RELEASE

Contact: Jan Vardaman
(512) 372-8887

FOR IMMEDIATE RELEASE
January 13, 2014

TechSearch International Study Details Renewed Interest in Embedded Components

Almost every application space in the electronics industry has evolved around a single goal—increase functionality while improving cost/performance. Many strategies and technologies have been introduced, including embedding components inside a printed circuit board or IC package. What's driving today's renewed interest for embedded active and passive functions?

TechSearch International's new study, **Embedded Components: Why Now? -- Markets, Applications, and Technologies**, provides unparalleled analysis of the underlying developments and trends in the industry based on the company's 26-year history of studying the market and critical infrastructure issues.

PCBs and IC packages with embedded passives have been in the market for many years. Dai Nippon Printing started shipping PCBs with embedded passive devices in 2006 and cumulative shipments total hundreds of millions of parts. A smartphone board contains more than 230 passive devices in the main board. Some modules also contain active devices. Casio shipped a power management module with an embedded WLP in its wristwatch in 2006, making it the first wearable electronics application with an embedded component. TI's MicroSiP™ is in volume production with its stand-alone power supply platform (DC-DC voltage converter) for portable applications. Infineon is shipping its DrBlade low-voltage DC-DC voltage regulator for computing, telecommunication, servers (Blade and Rack), PCs, and gaming machines.

Formed resistors have been widely employed in the defense and aerospace industry. New applications in the consumer space, telecom, computing, and industrial areas are expanding the market. Planar capacitance has been utilized in the high-performance computing and communication segments for many years. With the higher capacitance levels now available, the market is expanding into IC packages and modules.

This report analyzes the expanding wide range of markets providing insight into the drivers, applications, and future growth. Fan-out wafer level packages are included in the analysis. A discussion of the challenges posed by embedded solutions and the potential impact of the technology on the supply chain is included.

The 134-page report with full references provides an in-depth analysis of the activities of various companies explaining current and future products with specific examples of the use of embedded components. Forecasts are provided for the placed embedded active and passive components, as well as the markets for embedded formed resistors and capacitors. A complimentary set of PowerPoint slides accompanies the report.

TechSearch International, Inc., founded in 1987, is market research leader specializing in technology trends microelectronics packaging and assembly. Multi- and single-client services encompass technology licensing, strategic planning, and market and technology analysis. TechSearch International professionals have an extensive network of more than 15,000 contacts in North America, Asia, and Europe. For more information, contact TechSearch at tel: 512-372-8887, fax: 512-372-8889, or <http://www.techsearchinc.com>.